

# Customer Service Note

## Product Mark/Label

### Introduction

Micron now has two product mark variations to accommodate smaller components and different package sizes (for example, FBGA, CSP). Both product marks are right- and left-justified and have a character height of 0.040–0.050 inches depending on package size. Both marks also include a unique, laser-inscribed identification number on the top side of the part for traceability purposes.

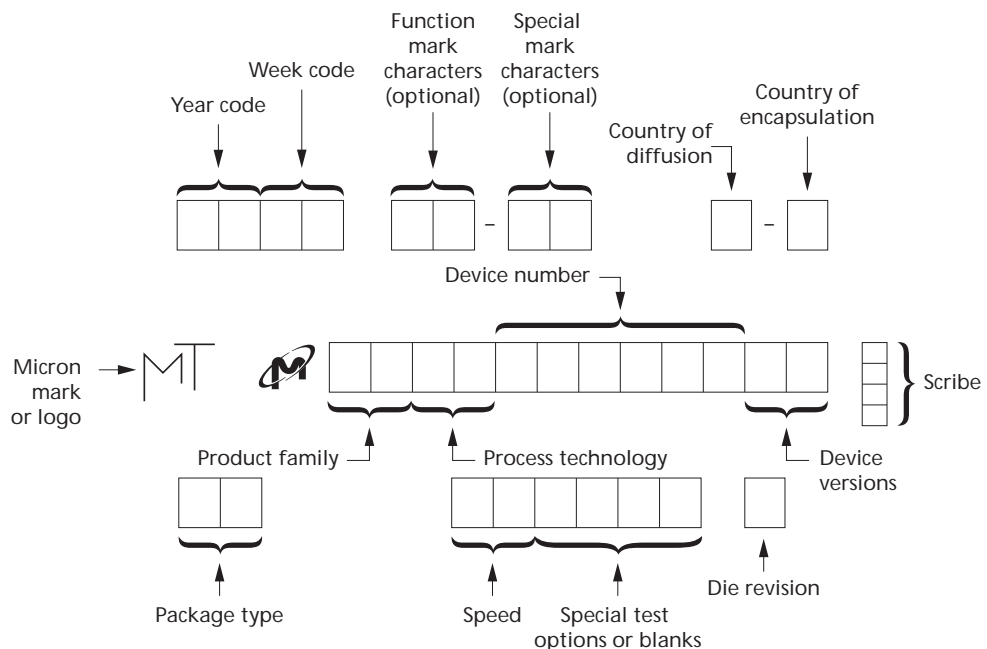
### Component Mark Information

Most component marks contain the following details (see Figure 1):

- Date code (work week and year)
- Special mark characters
- Country of diffusion<sup>1</sup>
- Country of encapsulation<sup>1</sup>
- Micron<sup>®</sup> mark or logo
- Product family
- Process technology
- Device number
- Device versions
- Package type
- Speed
- Special test option (if relevant)
- Die revision
- Scribe

Notes appear on page 2.

Figure 1: TSOP Component Mark



## Abbreviated Component Mark Information

Due to space limitations, FBGA-package component marks contain abbreviated details for two distinct types of information (see Figure 2). The top row of the component mark contains details unrelated to product type:

- Date code (work week and year)<sup>2</sup>
- Die revision
- Country of diffusion<sup>1</sup>
- Country of encapsulation<sup>1</sup>

The middle and bottom rows of the component mark contain product-specific details such as:

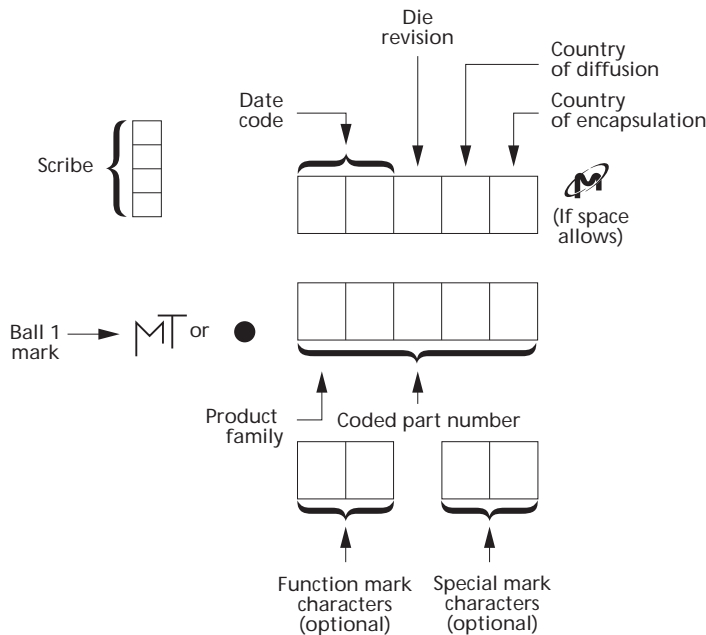
- Micron logo/ball 1 designator
- Product family
- Coded part number
- Special mark characters

For more information on product-specific designators, see the part numbering guides on Micron's Web site: [www.micron.com](http://www.micron.com). Abbreviated date codes for FBGA packages are also available in the part numbering guides on our Web site.

- Notes:
1. Codes for the countries of diffusion and encapsulation:
 

1 = USA	4 = Japan	8 = Korea
2 = Singapore	5 = China	
3 = Italy	7 = Taiwan	
  2. The Micron FBGA Part Marking Decoder, which provides the corresponding part numbers for part mark codes, is available at [www.micron.com/decoder](http://www.micron.com/decoder).

Figure 2: BGA/LGA Abbreviated Component Mark

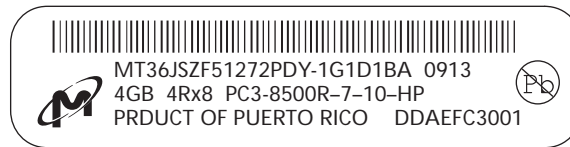


## Module Label Information

Labels typically used for module production have standard requirements for each line printed on the label (see Figure 3):

- Line 1: Code 128 subset B bar code of Micron part number
- Line 2: Marketing part number/date code
- Line 3: JEDEC label as appropriate/optional project number
- Line 4: Module assembly country of origin/lot ID code

Figure 3: Module Label



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## Revision History

<b>Rev. E</b> .....		<b>10/09</b>
	<ul style="list-style-type: none"><li>• Updated template</li><li>• Updated Figure 3, "Module Label"</li></ul>	
<b>Rev. D</b> .....		<b>6/08</b>
	<ul style="list-style-type: none"><li>• Added Korea to note 1 country codes</li><li>• Updated and renamed Figure 2</li><li>• Deleted Figure 3, "DDR2/GDDR3 FBGA Abbreviated Component Mark"</li></ul>	
<b>Rev. C</b> .....		<b>5/07</b>
	<ul style="list-style-type: none"><li>• Added Taiwan to note 1 country codes</li></ul>	
<b>Rev. 12/9/05</b>		
	<ul style="list-style-type: none"><li>• Added logo information to Figure 1 on page 1 and Figure 2 on page 2</li></ul>	
<b>Rev. 2/14/05</b>		
	<ul style="list-style-type: none"><li>• Added China to note 1 country codes</li></ul>	